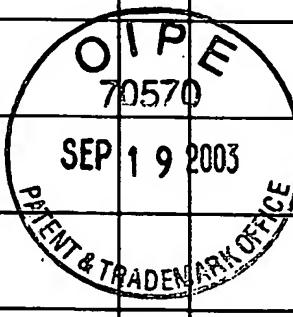


Substitute for form 1449A/PTO				<i>Complete if Known</i>	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT				Application Number	Not yet assigned 10/667798
				Filing Date	Herewith
				First Named Inventor	RATIFICAR, Glenn
				Group Art Unit	Not yet assigned 2891
				Examiner Name	Not yet assigned ZARNEKE
Sheet	1	of	1	Attorney Docket Number	P16916

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS				
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		
<i>GL</i>	A	Gilleo, Ken Dr. and Blumel, David., "The Ultimate Flip Chip – Integrated Flux/Underfill", Alpha Metals. 12pgs.		
	B	Babiarz, Alex J. and Huysmans, Frank, "Advances in Dispensing Processes for Flip Chip Underfill", ISHM Nordic 34 th Annual Conference, Asymtek, Carlsbad, CA, 7pgs.		
<i>JH</i>	C	Hurley, James M. et al., "Kinetic Modeling of No-Flow Underfill Cure and Its Relationship to Solder Wetting and Voiding", Cookson Semiconductor Packaging Materials, Alpharetta, GA, 8pgs.		
<i>JH</i>	D	Hurley, James M. et al., "Possibilities and Limitations of No-Flow Fluxing Underfill", Cookson Electronics – Semiconductor Products, Alpharetta, GA, ©2002 IEEE, 6pgs.		
				
Examiner Signature	<i>Glenn J. H.</i>		Date Considered	9/13/06

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹Unique citation designation number. ²Applicant is to place a check mark here if English language Translation is attached.